
HAT1031T

Silicon P Channel Power MOS FET
High Speed Power Switching

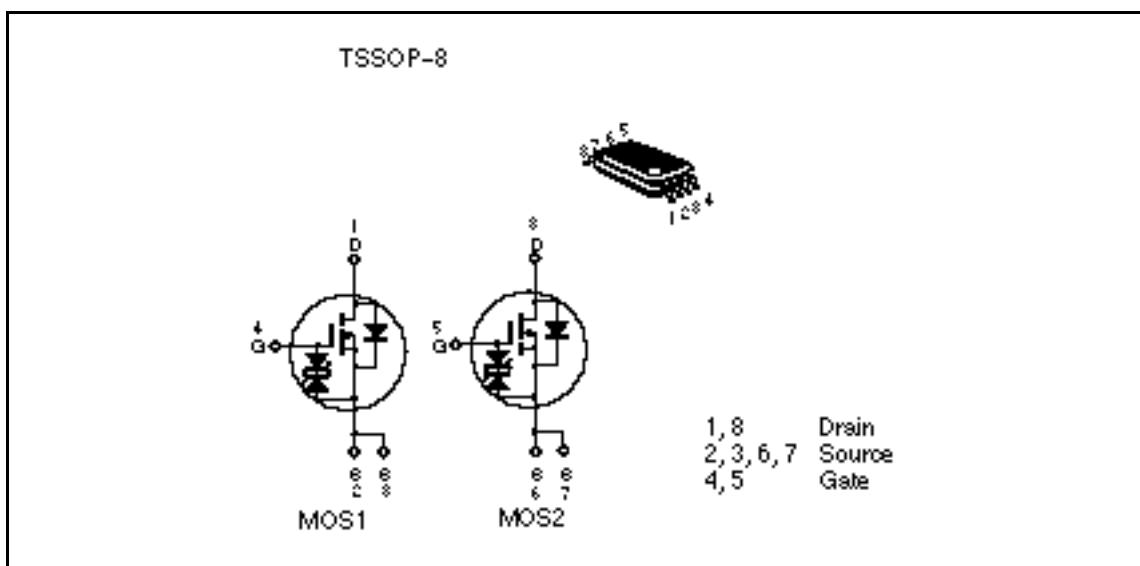
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ADE-208-528D (Z)
5th. Edition
December 1998

Features

- Low on-resistance
- Capable of 2.5 V gate drive
- Low drive current
- High density mounting

Outline



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Absolute Maximum Ratings (Ta = 25°C)

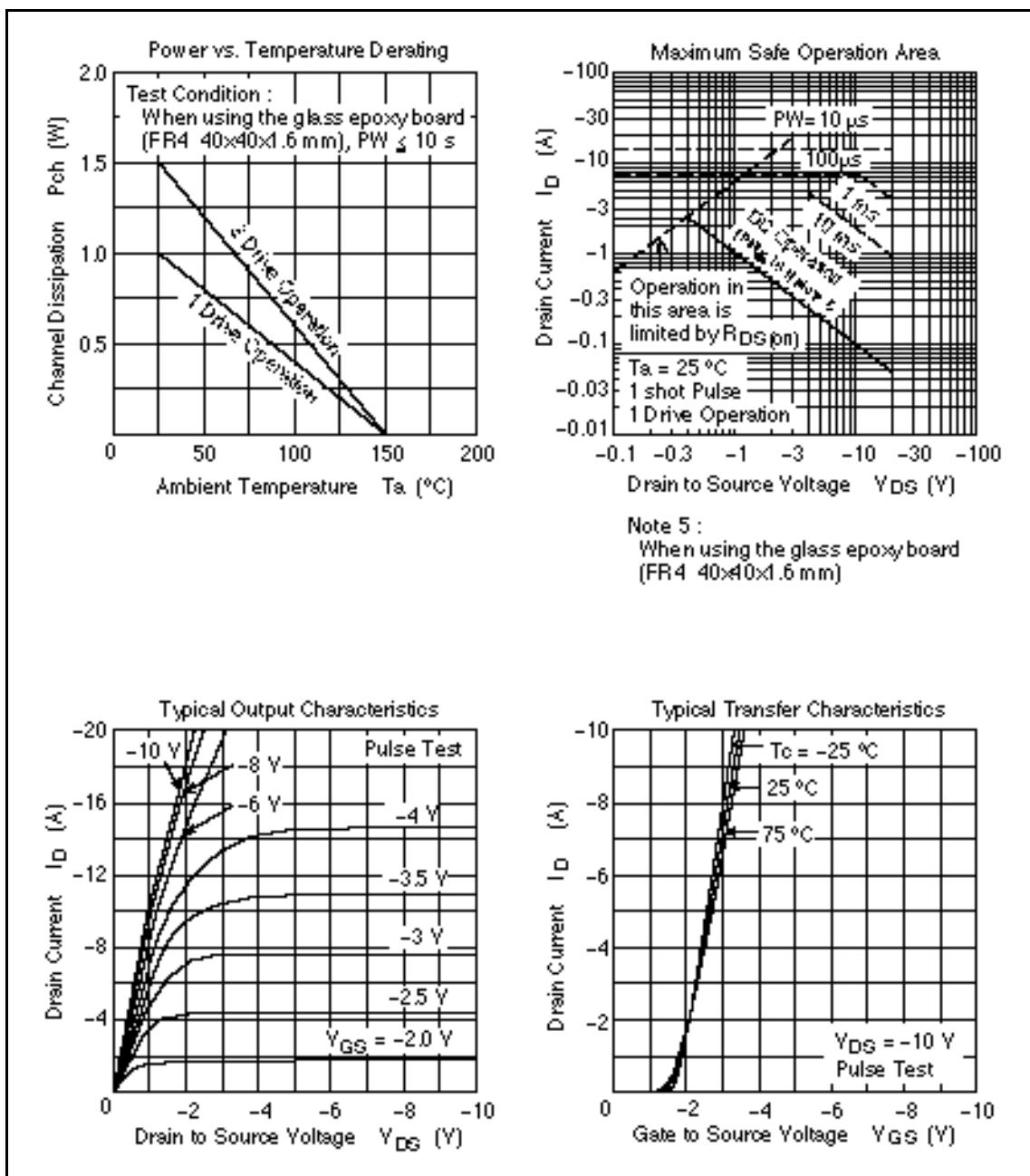
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	-20	V
Gate to source voltage	V _{GSS}	±10	V
Drain current	I _D	-2.5	A
Drain peak current	I _{D(pulse)} ^{Note1}	-20	A
Body-drain diode reverse drain current	I _{DR}	-2.5	A
Channel dissipation	Pch ^{Note2}	1	W
Channel dissipation	Pch ^{Note3}	1.5	W
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{tstg}	-55 to +150	°C

- Note:
1. PW 10µs, duty cycle 1 %
 2. 1 Drive operation ; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW 10s
 3. 2 Drive operation ; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW 10s

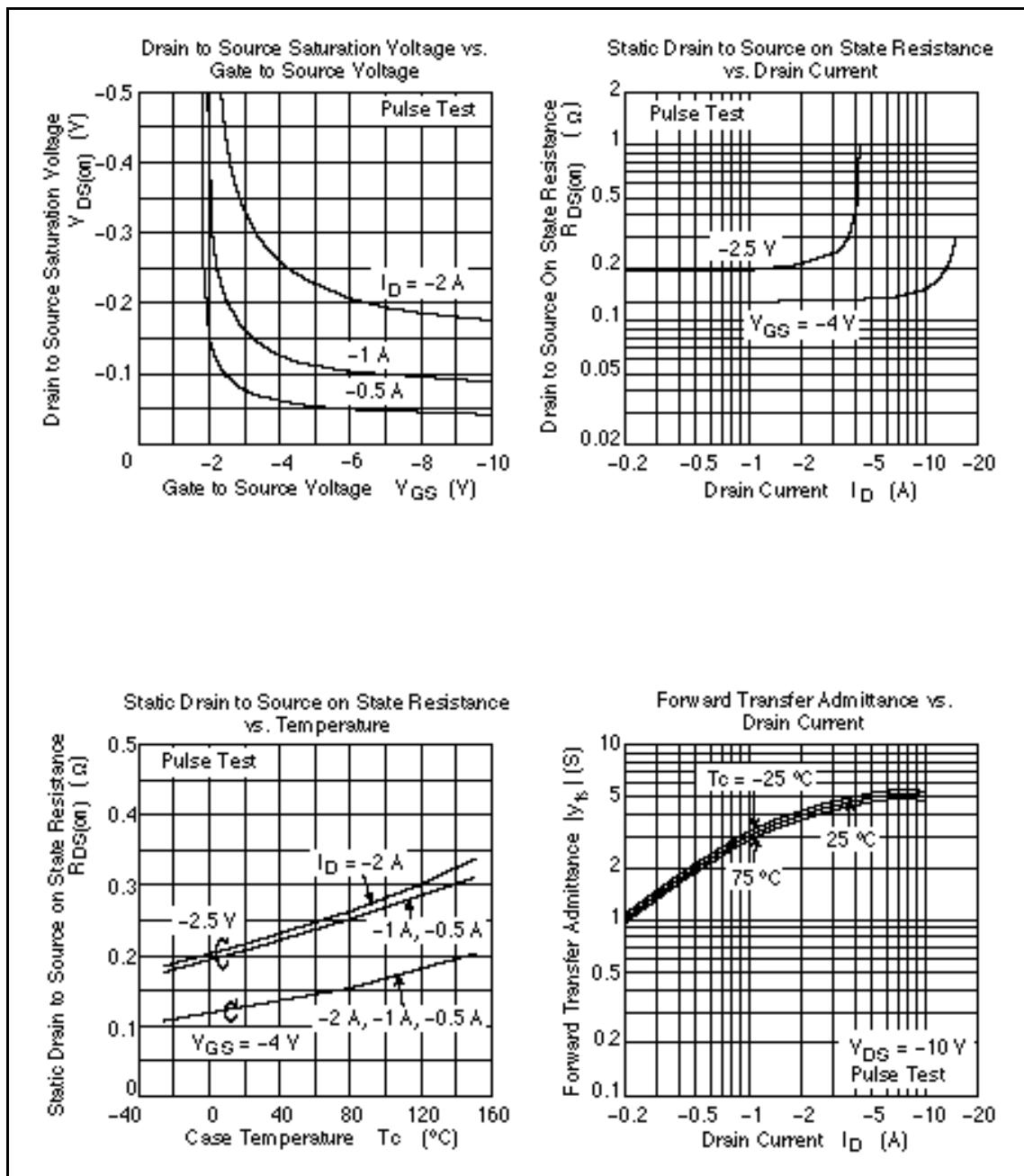
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	-20	—	—	V	I _D = -10mA, V _{GS} = 0
Gate to source breakdown voltage	V _{(BR)GSS}	±10	—	—	V	I _G = ±100µA, V _{DS} = 0
Gate to source leak current	I _{GSS}	—	—	±10	µA	V _{GS} = ±8V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	-1	µA	V _{DS} = -20 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	-0.5	—	-1.5	V	V _{DS} = -10V, I _D = -1mA
Static drain to source on state resistance	R _{DS(on)}	—	0.13	0.16		I _D = -2A, V _{GS} = -4V ^{Note4}
Forward transfer admittance	y _{fs}	2.6	4	—	S	I _D = -2A, V _{DS} = -10V ^{Note4}
Input capacitance	C _{iss}	—	390	—	pF	V _{DS} = -10V
Output capacitance	C _{oss}	—	200	—	pF	V _{GS} = 0
Reverse transfer capacitance	C _{rss}	—	70	—	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	—	14	—	ns	V _{GS} = -4V, I _D = -2A
Rise time	t _r	—	75	—	ns	V _{DD} = -10V
Turn-off delay time	t _{d(off)}	—	60	—	ns	
Fall time	t _f	—	55	—	ns	
Body-drain diode forward voltage	V _{DF}	—	-0.9	-1.17	V	IF = -2.5A, V _{GS} = 0 ^{Note4}
Body-drain diode reverse recovery time	t _{rr}	—	45	—	ns	IF = -2.5A, V _{GS} = 0 dI/dt = 20A/µs

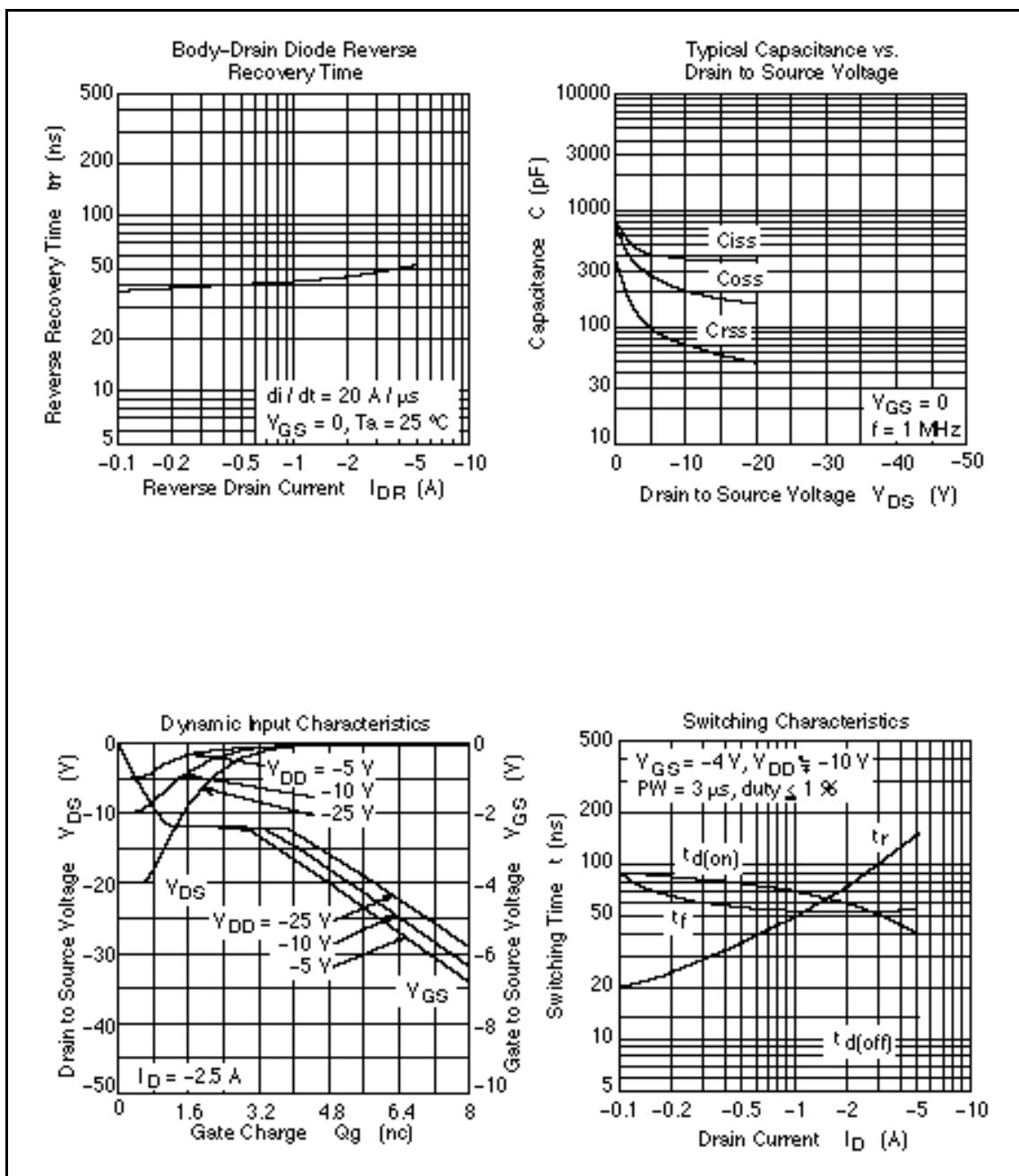
- Note:
4. Pulse test

Main Characteristics

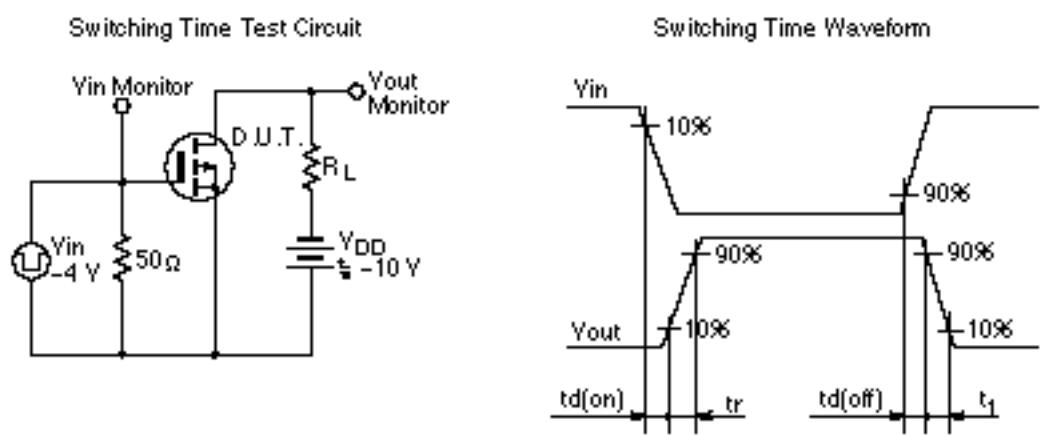
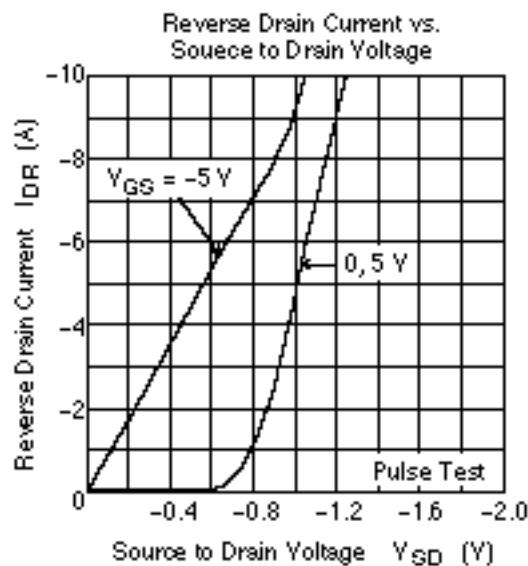
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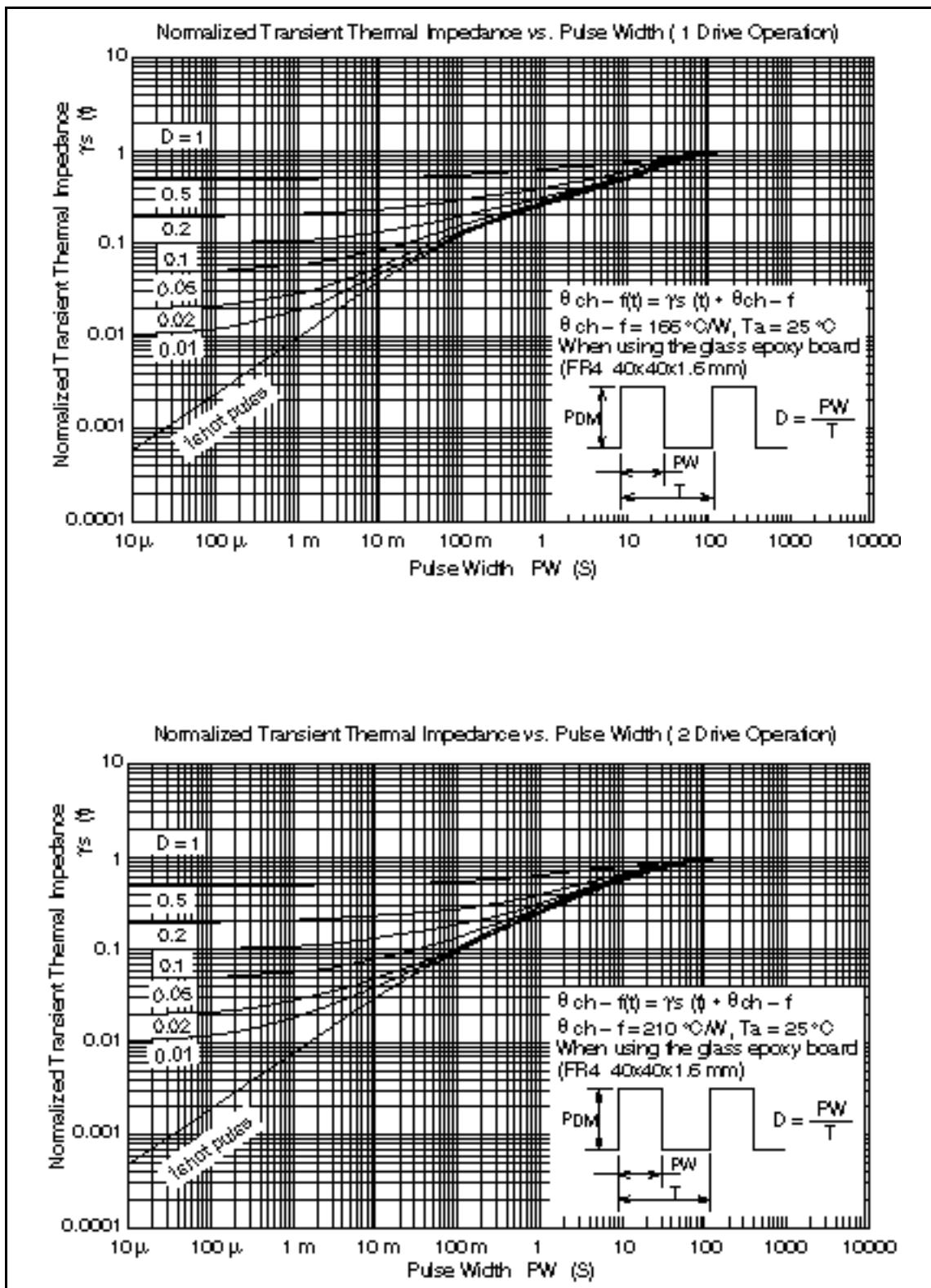


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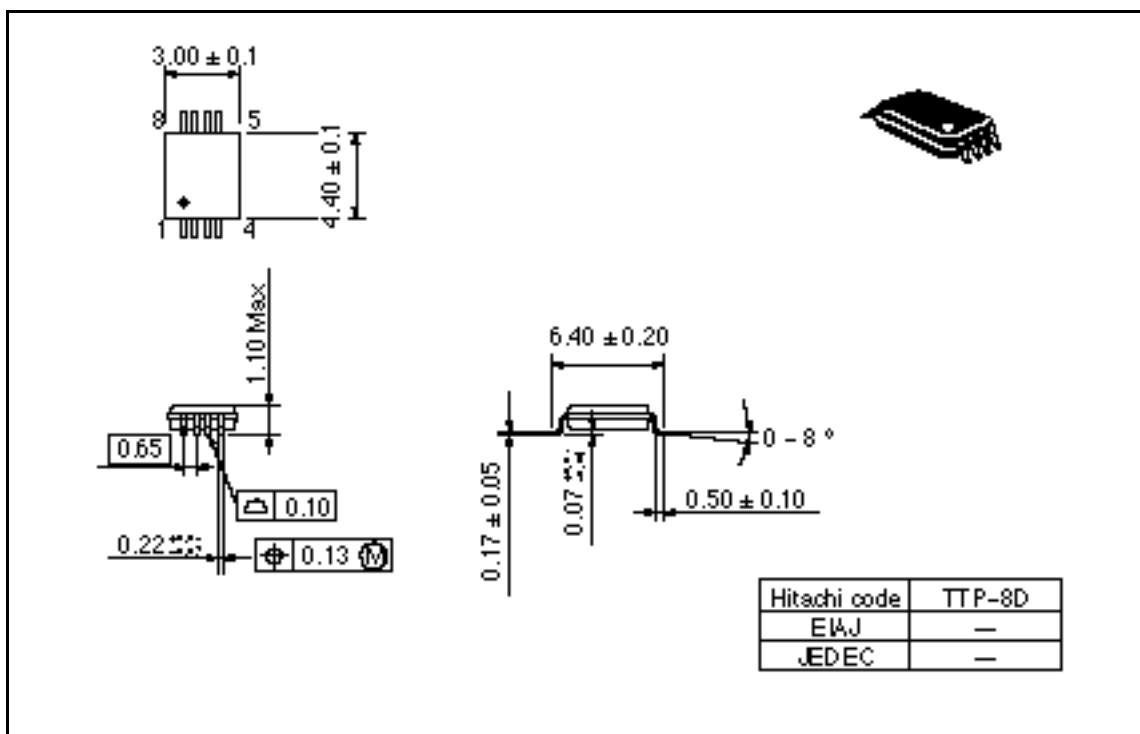
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**Package Dimensions**

Unit: mm

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